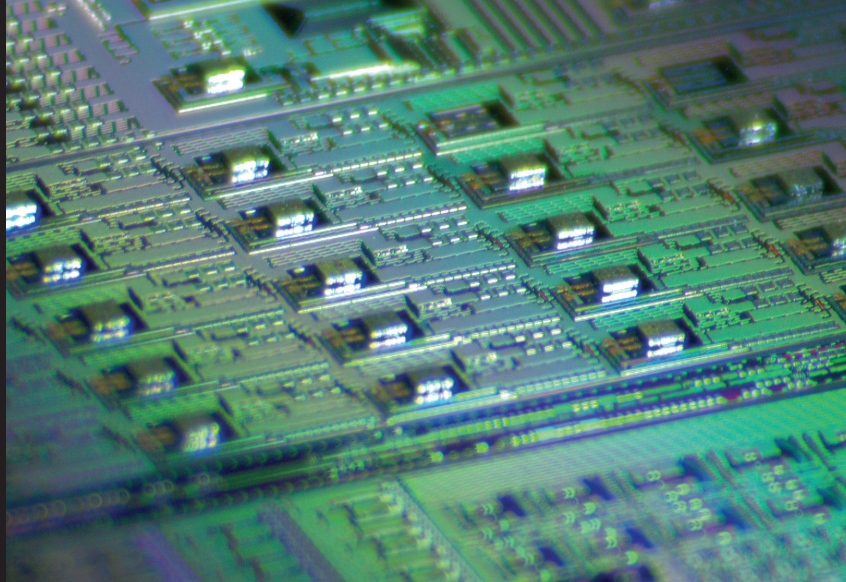
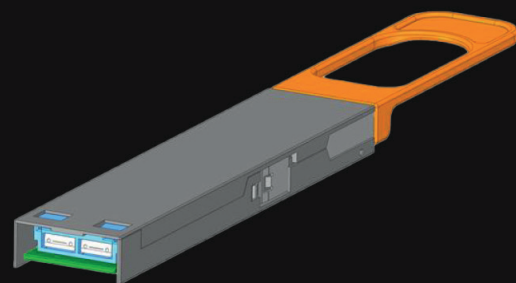


Multi-spectral ELS for Scale-Up



Main Features

- ▶ **OCI-MSA compliant**, bare chip engine and OIF-ELSFP form factor with blind-mate optical interface
- ▶ **8 wavelengths on OCI-MSA grid**, groups A and B, 1308.00 to 1334.78 nm
- ▶ **> 16 dBm per wavelength in fiber**, up to 24 dBm aggregated per PM fiber
- ▶ **Absolute wavelength lock to ± 0.1 nm**, held without an external wavelength reference
- ▶ **Low thermal wavelength sensitivity**
- ▶ **< 100 kHz linewidth**, constant across the full power range
- ▶ **14 dB programmed output range**, wavelength-invariant
- ▶ **Flip-chip integrated known-good-die**, wafer-scale passive alignment



Optical specifications

Parameter	Min	Typ	Max	Unit
Wavelengths, OCI grid A and B	8			
Wavelength accuracy, absolute, over life and temperature	-0.2	± 0.1	+0.2	nm
Wavelength temperature coefficient		13		pm/K
Output power per wavelength, in fiber	16			dBm
Aggregated output power per fiber			24	dBm
Commandable attenuation range, ΔP_{ELS}	0		14	dB
Wavelength shift over the full attenuation range			± 0.02	nm
Linewidth		50	100	kHz
RIN, 0.1 to 20 GHz		-157	-150	dB/Hz
Side-mode suppression ratio	45	55		dB
Polarisation extinction ratio	20	23		dB
Output reflectance			-26	dB
Optical return loss tolerance			-26	dB

Electrical, thermal and mechanical

Parameter	Typ	Max	Unit
Power consumption, full output	23	25	W
Power consumption, minimum output	6		W
ELSFP power class	6		
Substrate temperature		60	°C
Optical interface	MT-12, 2 PM fibers, blind-mate, Conventional keying		
Initialisation time	500		ms

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